



**THE DATASHEET OF
IS64LF25636B-7.5B3LA3**



**256K x 36, 512K x 18
9 Mb SYNCHRONOUS FLOW-THROUGH
STATIC RAM**

MARCH 2020

FEATURES

- Internal self-timed write cycle
- Individual Byte Write Control and Global Write
- Clock controlled, registered address, data and control
- Burst sequence control using MODE input
- Three chip enable option for simple depth expansion and address pipelining
- Common data inputs and data outputs
- Auto Power-down during deselect
- Single cycle deselect
- Snooze MODE for reduced-power standby
- JTAG Boundary Scan for BGA package
- Power Supply
 LF: VDD 3.3V ($\pm 5\%$), VDDQ 3.3V/2.5V ($\pm 5\%$)
 VF: VDD 2.5V ($\pm 5\%$), VDDQ 2.5V ($\pm 5\%$)
 VVF: VDD 1.8V ($\pm 5\%$), VDDQ 1.8V ($\pm 5\%$)
- JEDEC 100-Pin QFP, 119-pin BGA, and 165-pin BGA packages
- Lead-free available

DESCRIPTION

The 9Mb product family features high-speed, low-power synchronous static RAMs designed to provide burstable, high-performance memory for communication and networking applications. The IS61(64)LF/VF25636B is organized as 262,144 words by 36 bits. The IS61(64)LF/VF51218B is organized as 524,288 words by 18 bits. Fabricated with ISSI's advanced CMOS technology, the device integrates a 2-bit burst counter, high-speed SRAM core, and high-drive capability outputs into a single monolithic circuit. All synchronous inputs pass through registers controlled by a positive-edge-triggered single clock input.

Write cycles are internally self-timed and are initiated by the rising edge of the clock input. Write cycles can be one to four bytes wide as controlled by the write control inputs.

Separate byte enables allow individual bytes to be written. Byte write operation is performed by using byte write enable (\overline{BWE}) input combined with one or more individual byte write signals (BWx). In addition, Global Write (\overline{GW}) is available for writing all bytes at one time, regardless of the byte write controls.

Bursts can be initiated with either \overline{ADSP} (Address Status Processor) or \overline{ADSC} (Address Status Cache Controller) input pins. Subsequent burst addresses can be generated internally and controlled by the \overline{ADV} (burst address advance) input pin.

The mode pin is used to select the burst sequence order, Linear burst is achieved when this pin is tied LOW. Interleave burst is achieved when this pin is tied HIGH or left floating.

FAST ACCESS TIME

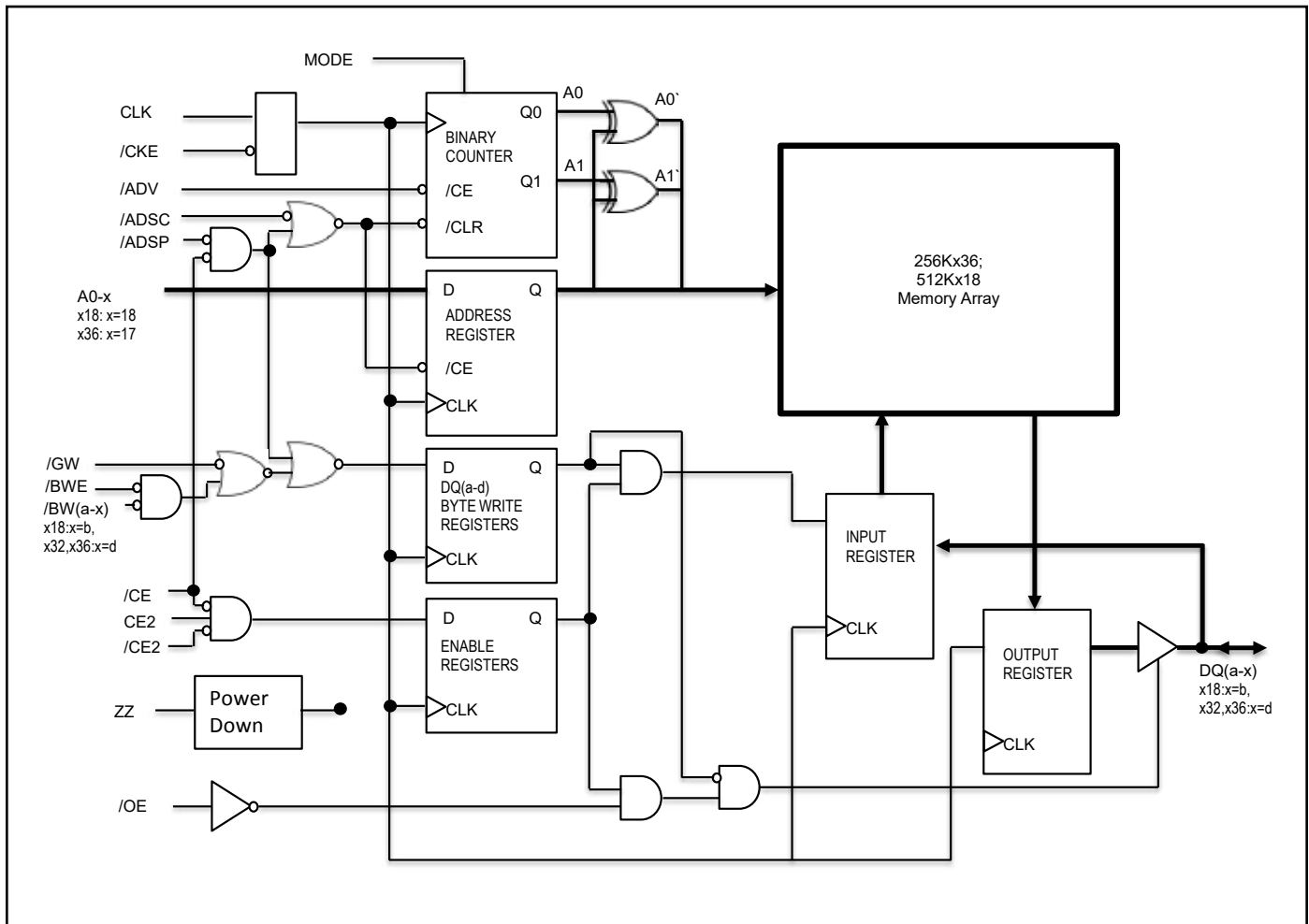
Symbol	Parameter	-6.5	-7.5	Units
tKQ	Clock Access Time	6.5	7.5	ns
tKc	Cycle Time	7.5	8.5	ns
	Frequency	133	117	MHz

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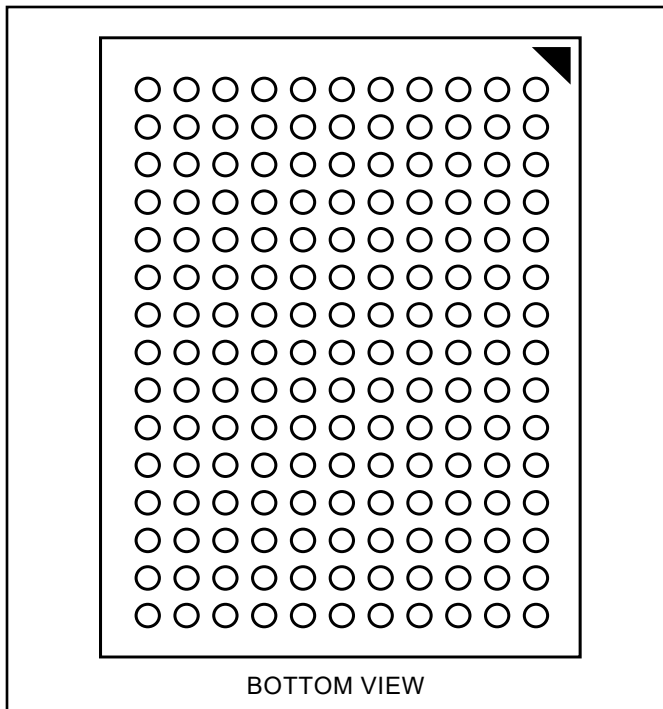
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BLOCK DIAGRAM



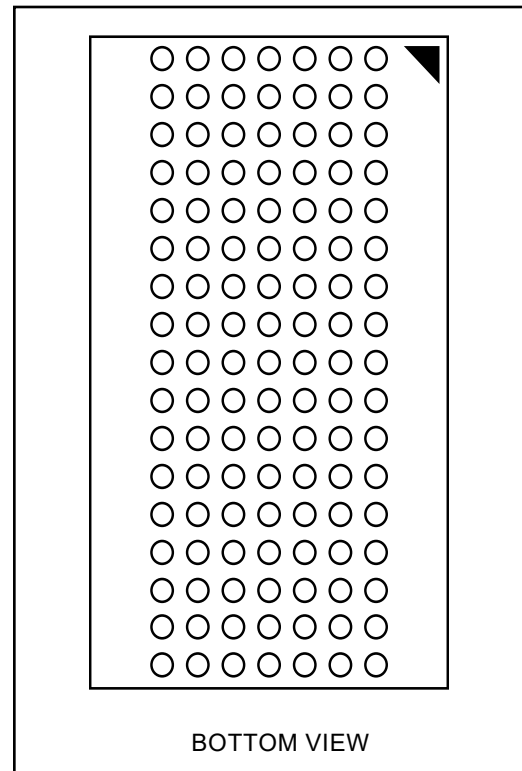
165-PIN BGA

165-Ball, 13x15 mm BGA



119-PIN BGA

119-Ball, 14x22 mm BGA



119 BGA PACKAGE PIN CONFIGURATION-256K x 36 (TOP VIEW)

	1	2	3	4	5	6	7
A	V _{DDQ}	A	A	$\overline{\text{ADSP}}$	A	A	V _{DDQ}
B	NC	CE2	A	$\overline{\text{ADSC}}$	A	A	NC
C	NC	A	A	V _{DD}	A	A	NC
D	DQc	DQPc	V _{SS}	NC	V _{SS}	DQPb	DQb
E	DQc	DQc	V _{SS}	$\overline{\text{CE}}$	V _{SS}	DQb	DQb
F	V _{DDQ}	DQc	V _{SS}	$\overline{\text{OE}}$	V _{SS}	DQb	V _{DDQ}
G	DQc	DQc	$\overline{\text{BWc}}$	$\overline{\text{ADV}}$	$\overline{\text{BWb}}$	DQb	DQb
H	DQc	DQc	V _{SS}	$\overline{\text{GW}}$	V _{SS}	DQb	DQb
J	V _{DDQ}	V _{DD}	NC	V _{DD}	NC	V _{DD}	V _{DDQ}
K	DQd	DQd	V _{SS}	CLK	V _{SS}	DQa	DQa
L	DQd	DQd	$\overline{\text{BWd}}$	NC	$\overline{\text{BWa}}$	DQa	DQa
M	V _{DDQ}	DQd	V _{SS}	$\overline{\text{BWE}}$	V _{SS}	DQa	V _{DDQ}
N	DQd	DQd	V _{SS}	A ₁ *	V _{SS}	DQa	DQa
P	DQd	DQPd	V _{SS}	A ₀ *	V _{SS}	DQPd	DQa
R	NC	A	MODE	V _{DD}	NC	A	NC
T	NC	NC	A	A	A	NC	ZZ
U	V _{DDQ}	TMS	TDI	TCK	TDO	NC	V _{DDQ}

Note: * A₀ and A₁ are the two least significant bits (LSB) of the address field and set the internal burst counter if burst is desired.

PIN DESCRIPTIONS

Symbol	Pin Name
A	Address Inputs
A ₀ , A ₁	Synchronous Burst Address Inputs
$\overline{\text{ADV}}$	Synchronous Burst Address Advance
$\overline{\text{ADSP}}$	Address Status Processor
$\overline{\text{ADSC}}$	Address Status Controller
$\overline{\text{GW}}$	Global Write Enable
CLK	Synchronous Clock
$\overline{\text{CE}}$, CE2	Synchronous Chip Select
$\overline{\text{BWx}}$ (x=a-d)	Synchronous Byte Write Controls
$\overline{\text{BWE}}$	Byte Write Enable

Symbol	Pin Name
$\overline{\text{OE}}$	Output Enable
ZZ	Power Sleep Mode
MODE	Burst Sequence Selection
TCK, TDO	JTAG Pins
TMS, TDI	
NC	No Connect
DQa-DQd	Data Inputs/Outputs
DQPd-Pa	Parity Data Inputs/Outputs
V _{DD}	Power Supply
V _{DDQ}	I/O Power Supply
V _{SS}	Ground

119 BGA PACKAGE PIN CONFIGURATION

512Kx18 (TOP VIEW)

	1	2	3	4	5	6	7
A	V _{DDQ}	A	A	$\overline{\text{ADSP}}$	A	A	V _{DDQ}
B	NC	CE2	A	$\overline{\text{ADSC}}$	A	A	NC
C	NC	A	A	V _{DD}	A	A	NC
D	DQ _b	NC	V _{SS}	NC	V _{SS}	DQP _a	NC
E	NC	DQ _b	V _{SS}	$\overline{\text{CE}}$	V _{SS}	NC	DQ _a
F	V _{DDQ}	NC	V _{SS}	$\overline{\text{OE}}$	V _{SS}	DQ _a	V _{DDQ}
G	NC	DQ _b	$\overline{\text{BWb}}$	$\overline{\text{ADV}}$	V _{SS}	NC	DQ _a
H	DQ _b	NC	V _{SS}	$\overline{\text{GW}}$	V _{SS}	DQ _a	NC
J	V _{DDQ}	V _{DD}	NC	V _{DD}	NC	V _{DD}	V _{DDQ}
K	NC	DQ _b	V _{SS}	CLK	V _{SS}	NC	DQ _a
L	DQ _b	NC	V _{SS}	NC	$\overline{\text{BWa}}$	DQ _a	NC
M	V _{DDQ}	DQ _b	V _{SS}	$\overline{\text{BWE}}$	V _{SS}	NC	V _{DDQ}
N	DQ _b	NC	V _{SS}	A ₁ *	V _{SS}	DQ _a	NC
P	NC	DQP _b	V _{SS}	A ₀ *	V _{SS}	NC	DQ _a
R	NC	A	MODE	V _{DD}	NC	A	NC
T	NC	A	A	NC	A	A	ZZ
U	V _{DDQ}	TMS	TDI	TCK	TDO	NC	V _{DDQ}

Note: * A₀ and A₁ are the two least significant bits (LSB) of the address field and set the internal burst counter if burst is desired.

PIN DESCRIPTIONS

Symbol	Pin Name
A	Address Inputs
A0, A1	Synchronous Burst Address Inputs
$\overline{\text{ADV}}$	Synchronous Burst Address Advance
$\overline{\text{ADSP}}$	Address Status Processor
$\overline{\text{ADSC}}$	Address Status Controller
$\overline{\text{GW}}$	Global Write Enable
CLK	Synchronous Clock
$\overline{\text{CE}}$, CE2	Synchronous Chip Select
$\overline{\text{BWx}}$ (x=a,b)	Synchronous Byte Write Controls
$\overline{\text{BWE}}$	Byte Write Enable

Symbol	Pin Name
$\overline{\text{OE}}$	Output Enable
ZZ	Power Sleep Mode
MODE	Burst Sequence Selection
TCK, TDO	JTAG Pins
TMS, TDI	
NC	No Connect
DQ _a -DQ _b	Data Inputs/Outputs
DQP _a -P _b	Parity Data Inputs/Outputs
V _{DD}	Power Supply
V _{DDQ}	I/O Power Supply
V _{SS}	Ground

165 BGA PACKAGE PIN CONFIGURATION

256K x 36 (TOP VIEW)

	1	2	3	4	5	6	7	8	9	10	11
A	NC	A	\overline{CE}	\overline{BWc}	\overline{BWb}	$\overline{CE2}$	\overline{BWE}	\overline{ADSC}	\overline{ADV}	A	NC
B	NC	A	CE2	\overline{BWd}	\overline{BWa}	CLK	\overline{GW}	\overline{OE}	\overline{ADSP}	A	NC
C	DQPc	NC	VDDQ	Vss	Vss	Vss	Vss	Vss	VDDQ	NC	DQPb
D	DQc	DQc	VDDQ	VDD	Vss	Vss	Vss	VDD	VDDQ	DQb	DQb
E	DQc	DQc	VDDQ	VDD	Vss	Vss	Vss	VDD	VDDQ	DQb	DQb
F	DQc	DQc	VDDQ	VDD	Vss	Vss	Vss	VDD	VDDQ	DQb	DQb
G	DQc	DQc	VDDQ	VDD	Vss	Vss	Vss	VDD	VDDQ	DQb	DQb
H	NC	Vss	NC	VDD	Vss	Vss	Vss	VDD	NC	NC	ZZ
J	DQd	DQd	VDDQ	VDD	Vss	Vss	Vss	VDD	VDDQ	DQa	DQa
K	DQd	DQd	VDDQ	VDD	Vss	Vss	Vss	VDD	VDDQ	DQa	DQa
L	DQd	DQd	VDDQ	VDD	Vss	Vss	Vss	VDD	VDDQ	DQa	DQa
M	DQd	DQd	VDDQ	VDD	Vss	Vss	Vss	VDD	VDDQ	DQa	DQa
N	DQPd	NC	VDDQ	Vss	NC	NC	NC	Vss	VDDQ	NC	DQPd
P	NC	NC	A	A	TDI	A1*	TDO	A	A	A	A
R	MODE	NC	A	A	TMS	A0*	TCK	A	A	A	A

Note: * A0 and A1 are the two least significant bits (LSB) of the address field and set the internal burst counter if burst is desired.

PIN DESCRIPTIONS

Symbol	Pin Name
A	Address Inputs
A0, A1	Synchronous Burst Address Inputs
\overline{ADV}	Synchronous Burst Address Advance
\overline{ADSP}	Address Status Processor
\overline{ADSC}	Address Status Controller
\overline{GW}	Global Write Enable
CLK	Synchronous Clock
\overline{CE} , $\overline{CE2}$, CE2	Synchronous Chip Select
\overline{BWx} (x=a,b,c,d)	Synchronous Byte Write Controls

Symbol	Pin Name
\overline{BWE}	Byte Write Enable
\overline{OE}	Output Enable
ZZ	Power Sleep Mode
MODE	Burst Sequence Selection
TCK, TDO TMS, TDI	JTAG Pins
NC	No Connect
DQx	Data Inputs/Outputs
DQPx	Parity Data Inputs/Outputs
VDD	Power Supply
VDDQ	I/O Power Supply
Vss	Ground

165 BGA PACKAGE PIN CONFIGURATION

512K x 18 (TOP VIEW)

	1	2	3	4	5	6	7	8	9	10	11
A	NC	A	\overline{CE}	$BW\overline{b}$	NC	$\overline{CE2}$	\overline{BWE}	\overline{ADSC}	\overline{ADV}	A	A
B	NC	A	CE2	NC	$\overline{Bw\overline{a}}$	CLK	\overline{GW}	\overline{OE}	\overline{ADSP}	A	NC
C	NC	NC	VDDQ	Vss	Vss	Vss	Vss	Vss	VDDQ	NC	DQP _a
D	NC	DQ _b	VDDQ	VDD	Vss	Vss	Vss	VDD	VDDQ	NC	DQ _a
E	NC	DQ _b	VDDQ	VDD	Vss	Vss	Vss	VDD	VDDQ	NC	DQ _a
F	NC	DQ _b	VDDQ	VDD	Vss	Vss	Vss	VDD	VDDQ	NC	DQ _a
G	NC	DQ _b	VDDQ	VDD	Vss	Vss	Vss	VDD	VDDQ	NC	DQ _a
H	NC	Vss	NC	VDD	Vss	Vss	Vss	VDD	NC	NC	ZZ
J	DQ _b	NC	VDDQ	VDD	Vss	Vss	Vss	VDD	VDDQ	DQ _a	NC
K	DQ _b	NC	VDDQ	VDD	Vss	Vss	Vss	VDD	VDDQ	DQ _a	NC
L	DQ _b	NC	VDDQ	VDD	Vss	Vss	Vss	VDD	VDDQ	DQ _a	NC
M	DQ _b	NC	VDDQ	VDD	Vss	Vss	Vss	VDD	VDDQ	DQ _a	NC
N	DQP _b	NC	VDDQ	Vss	NC	NC	NC	Vss	VDDQ	NC	NC
P	NC	NC	A	A	TDI	A1*	TDO	A	A	A	A
R	MODE	NC	A	A	TMS	A0*	TCK	A	A	A	A

Note: * A0 and A1 are the two least significant bits (LSB) of the address field and set the internal burst counter if burst is desired.

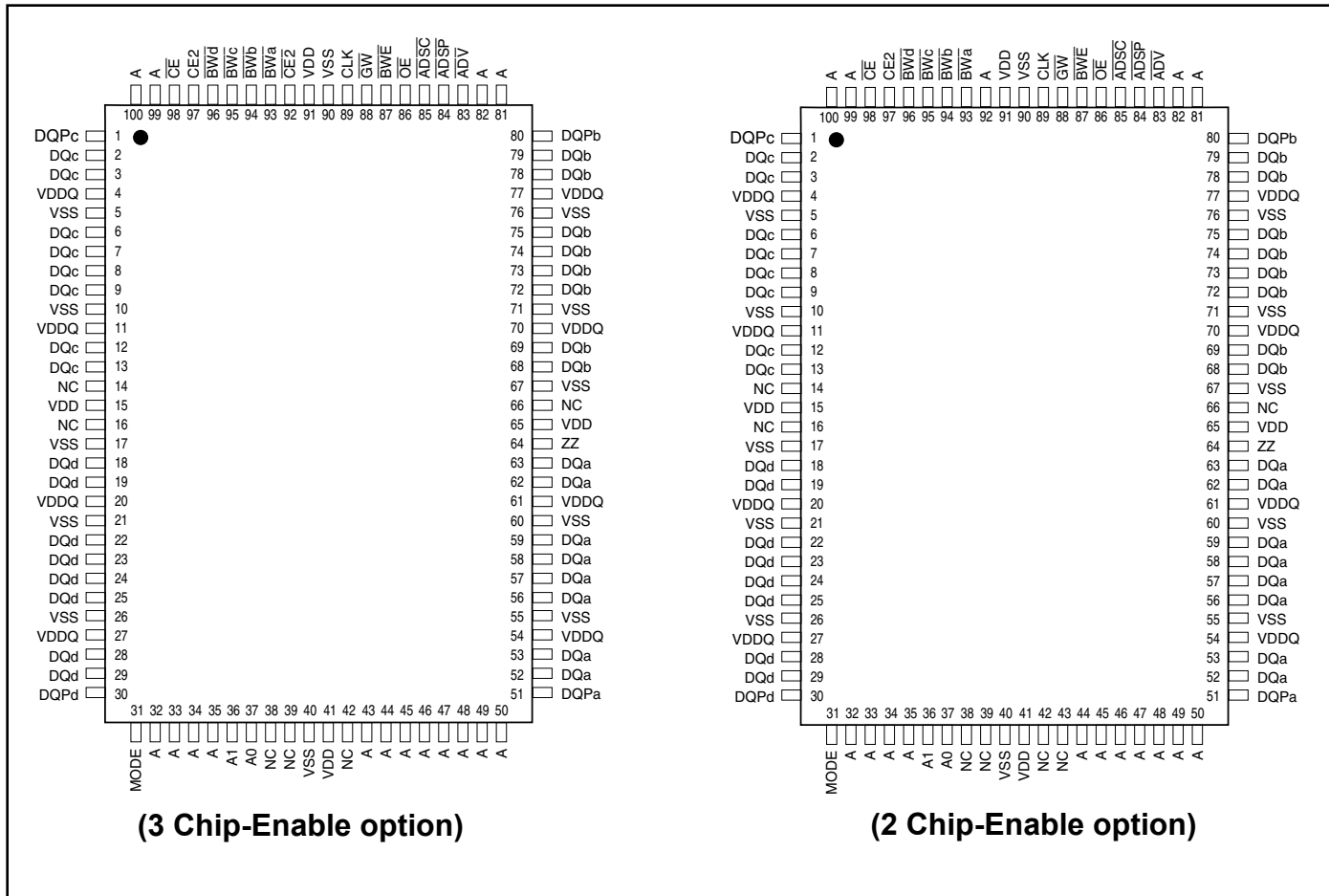
PIN DESCRIPTIONS

Symbol	Pin Name
A	Address Inputs
A0, A1	Synchronous Burst Address Inputs
\overline{ADV}	Synchronous Burst Address Advance
\overline{ADSP}	Address Status Processor
\overline{ADSC}	Address Status Controller
\overline{GW}	Global Write Enable
CLK	Synchronous Clock
\overline{CE} , $\overline{CE2}$, CE2	Synchronous Chip Select
\overline{BWx} (x=a,b)	Synchronous Byte Write Controls

Symbol	Pin Name
\overline{BWE}	Byte Write Enable
\overline{OE}	Output Enable
ZZ	Power Sleep Mode
MODE	Burst Sequence Selection
TCK, TDO TMS, TDI	JTAG Pins
NC	No Connect
DQ _x	Data Inputs/Outputs
DQP _x	Data Inputs/Outputs
VDD	Power Supply
VDDQ	I/O Power Supply
Vss	Ground

PIN CONFIGURATION

100-PIN QFP (256K X 36)



PIN DESCRIPTIONS

A0, A1	Synchronous Address Inputs. These pins must tied to the two LSBs of the address bus.
A	Synchronous Address Inputs
$\overline{\text{ADSC}}$	Synchronous Controller Address Status
$\overline{\text{ADSP}}$	Synchronous Processor Address Status
$\overline{\text{ADV}}$	Synchronous Burst Address Advance
$\overline{\text{BWA}}\text{-}\overline{\text{BWD}}$	Synchronous Byte Write Enable
$\overline{\text{BWE}}$	Synchronous Byte Write Enable
$\overline{\text{CE}}$, $\overline{\text{CE2}}$, $\overline{\text{CE2}}$	Synchronous Chip Enable
CLK	Synchronous Clock

DQa-DQd	Synchronous Data Input/Output
DQPa-DQPd	Parity Data Input/Output
$\overline{\text{GW}}$	Synchronous Global Write Enable
MODE	Burst Sequence Mode Selection
$\overline{\text{OE}}$	Output Enable
VDD	Power Supply
VDDQ	I/O Power Supply
Vss	Ground
ZZ	Snooze Enable

TRUTH TABLE⁽¹⁻⁸⁾

OPERATION	ADDRESS	\overline{CE}	$\overline{CE2}$	CE2	ZZ	\overline{ADSP}	\overline{ADSC}	\overline{ADV}	WRITE	\overline{OE}	CLK	DQ
Deselect Cycle, Power-Down	None	H	X	X	L	X	L	X	X	X	L-H	High-Z
Deselect Cycle, Power-Down	None	L	X	L	L	L	X	X	X	X	L-H	High-Z
Deselect Cycle, Power-Down	None	L	H	X	L	L	X	X	X	X	L-H	High-Z
Deselect Cycle, Power-Down	None	L	X	L	L	H	L	X	X	X	L-H	High-Z
Deselect Cycle, Power-Down	None	L	H	X	L	H	L	X	X	X	L-H	High-Z
Snooze Mode, Power-Down	None	X	X	X	H	X	X	X	X	X	X	High-Z
Read Cycle, Begin Burst	External	L	L	H	L	L	X	X	X	L	L-H	Q
Read Cycle, Begin Burst	External	L	L	H	L	L	X	X	X	H	L-H	High-Z
Write Cycle, Begin Burst	External	L	L	H	L	H	L	X	L	X	L-H	D
Read Cycle, Begin Burst	External	L	L	H	L	H	L	X	H	L	L-H	Q
Read Cycle, Begin Burst	External	L	L	H	L	H	L	X	H	H	L-H	High-Z
Read Cycle, Continue Burst	Next	X	X	X	L	H	H	L	H	L	L-H	Q
Read Cycle, Continue Burst	Next	X	X	X	L	H	H	L	H	H	L-H	High-Z
Read Cycle, Continue Burst	Next	H	X	X	L	X	H	L	H	L	L-H	Q
Read Cycle, Continue Burst	Next	H	X	X	L	X	H	L	H	H	L-H	High-Z
Write Cycle, Continue Burst	Next	X	X	X	L	H	H	L	L	X	L-H	D
Write Cycle, Continue Burst	Next	H	X	X	L	X	H	L	L	X	L-H	D
Read Cycle, Suspend Burst	Current	X	X	X	L	H	H	H	H	L	L-H	Q
Read Cycle, Suspend Burst	Current	X	X	X	L	H	H	H	H	H	L-H	High-Z
Read Cycle, Suspend Burst	Current	H	X	X	L	X	H	H	H	L	L-H	Q
Read Cycle, Suspend Burst	Current	H	X	X	L	X	H	H	H	H	L-H	High-Z
Write Cycle, Suspend Burst	Current	X	X	X	L	H	H	H	L	X	L-H	D
Write Cycle, Suspend Burst	Current	H	X	X	L	X	H	H	L	X	L-H	D

NOTE:

1. X means "Don't Care." H means logic HIGH. L means logic LOW.
2. For WRITE, L means one or more byte write enable signals ($\overline{BWA-d}$) and \overline{BWE} are LOW or \overline{GW} is LOW. WRITE = H for all \overline{BWx} , \overline{BWE} , \overline{GW} HIGH.
3. \overline{BWA} enables WRITES to DQa's and DQPa. \overline{BWb} enables WRITES to DQb's and DQPb. \overline{BWC} enables WRITES to DQc's and DQPC. \overline{BWD} enables WRITES to DQd's and DQPd. DQPa and DQPb are available on the x18 version. DQPa-DQPd are available on the x36 version.
4. All inputs except \overline{OE} and ZZ must meet setup and hold times around the rising edge (LOW to HIGH) of CLK.
5. Wait states are inserted by suspending burst.
6. For a WRITE operation following a READ operation, \overline{OE} must be HIGH before the input data setup time and held HIGH during the input data hold time.
7. This device contains circuitry that will ensure the outputs will be in High-Z during power-up.
8. \overline{ADSP} LOW always initiates an internal READ at the L-H edge of CLK. A WRITE is performed by setting one or more byte write enable signals and \overline{BWE} LOW or \overline{GW} LOW for the subsequent L-H edge of CLK. See WRITE timing diagram for clarification.

PARTIAL TRUTH TABLE

Function	\overline{GW}	\overline{BWE}	\overline{BWA}	\overline{BWb}	\overline{BWC}	\overline{BWD}
Read	H	H	X	X	X	X
Read	H	L	H	H	H	H
Write Byte 1	H	L	L	H	H	H
Write All Bytes	H	L	L	L	L	L
Write All Bytes	L	X	X	X	X	X

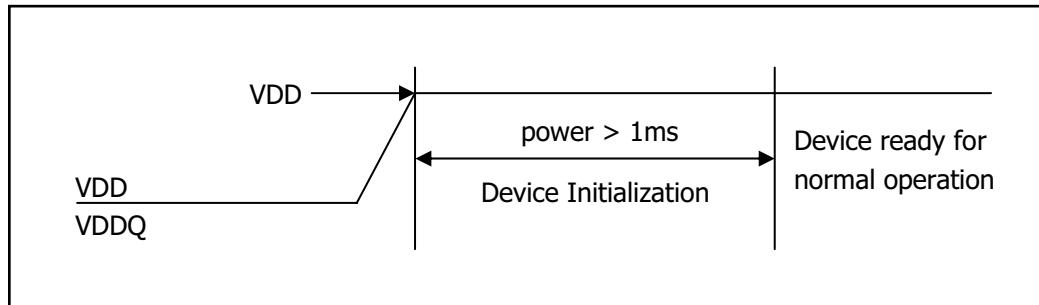
POWER UP SEQUENCE

$V_{DDQ} \rightarrow V_{DD}^1 \rightarrow I/O \text{ Pins}^2$

Notes:

1. V_{DD} can be applied at the same time as V_{DDQ}
2. Applying I/O inputs is recommended after V_{DDQ} is ready. The inputs of the I/O pins can be applied at the same time as V_{DDQ} provided V_{IH} (level of I/O pins) is lower than V_{DDQ} .

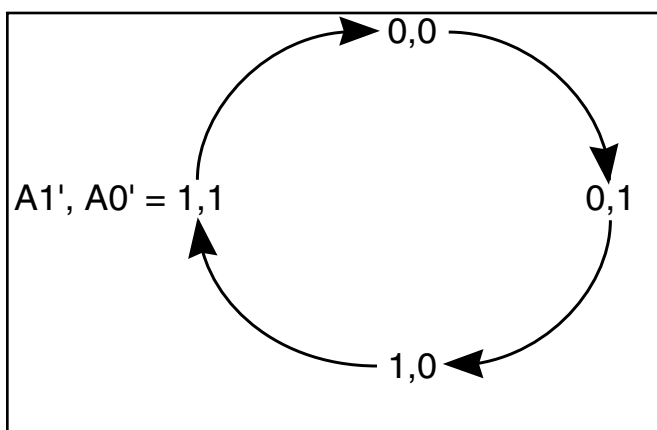
POWER-UP INITIALIZATION TIMING



INTERLEAVED BURST ADDRESS TABLE (MODE = V_{DD} or No Connect)

External Address A1 A0	1st Burst Address A1 A0	2nd Burst Address A1 A0	3rd Burst Address A1 A0
00	01	10	11
01	00	11	10
10	11	00	01
11	10	01	00

LINEAR BURST ADDRESS TABLE (MODE = V_{SS})



ABSOLUTE MAXIMUM RATINGS⁽¹⁾

Symbol	Parameter	LF Value	VF/VVF Value	Unit
T _{STG}	Storage Temperature	-55 to +150	-55 to +150	°C
P _D	Power Dissipation	1.6	1.6	W
I _{OUT}	Output Current (per I/O)	100	100	mA
V _{IN} , V _{OUT}	Voltage Relative to V _{SS} for I/O Pins	-0.5 to V _{DDQ} + 0.5	-0.5 to V _{DDQ} + 0.3	V
V _{IN}	Voltage Relative to V _{SS} for Address and Control Inputs	-0.5 to V _{DD} + 0.5	-0.5 to V _{DD} + 0.3	V
V _{DD}	Voltage on V _{DD} Supply Relative to V _{SS}	-0.5 to V _{DD} + 0.5	-0.3 to V _{DD} + 0.3	V

Notes:

1. Stress greater than those listed under ABSOLUTE MAXIMUM RATINGS may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.
2. This device contains circuitry to protect the inputs against damage due to high static voltages or electric fields; however, precautions may be taken to avoid application of any voltage higher than maximum rated voltages to this high-impedance circuit.
3. This device contains circuitry that will ensure the output devices are in High-Z at power up.

OPERATING RANGE (IS61/64LFxxxxx)

Range	Ambient Temperature	V _{DD}	V _{DDQ}
Commercial	0°C to +70°C	3.3V ± 5%	3.3V/2.5V ± 5%
Industrial	-40°C to +85°C	3.3V ± 5%	3.3V/2.5V ± 5%
Automotive(A3)	-40°C to +125°C	3.3V ± 5%	3.3V/2.5V ± 5%

OPERATING RANGE (IS61VFxxxxx)

Range	Ambient Temperature	V _{DD}	V _{DDQ}
Commercial	0°C to +70°C	2.5V ± 5%	2.5V ± 5%
Industrial	-40°C to +85°C	2.5V ± 5%	2.5V ± 5%

OPERATING RANGE (IS61VVFxxxxx)

Range	Ambient Temperature	V _{DD}	V _{DDQ}
Commercial	0°C to +70°C	1.8V ± 5%	1.8V ± 5%
Industrial	-40°C to +85°C	1.8V ± 5%	1.8V ± 5%

DC ELECTRICAL CHARACTERISTICS (Over Operating Range) ^{1, 2, 3}

Symbol	Parameter	Test Conditions	3.3V		2.5V		1.8V		Unit
			Min.	Max.	Min.	Max.	Min.	Max.	
V _{OH}	Output HIGH Voltage	I _{OH} = -4.0 mA (3.3V) I _{OH} = -1.0 mA (2.5V, 1.8V)	2.4	—	2.0	—	V _{DDQ} - 0.4	—	V
V _{OL}	Output LOW Voltage	I _{OL} = 8.0 mA (3.3V) I _{OL} = 1.0 mA (2.5V, 1.8V)	—	0.4	—	0.4	—	0.4	V
V _{IH}	Input HIGH Voltage		2.0	V _{DD} + 0.3	1.7	V _{DD} + 0.3	0.6V _{DD}	V _{DD} + 0.3	V
V _{IL}	Input LOW Voltage		-0.3	0.8	-0.3	0.7	-0.3	0.3V _{DD}	V
I _{LI}	Input Leakage Current	V _{SS} ≤ V _{IN} ≤ V _{DD} ⁽¹⁾	-5	5	-5	5	-5	5	μA
I _{LO}	Output Leakage Current	V _{SS} ≤ V _{OUT} ≤ V _{DDQ} , OE = V _{IH}	-5	5	-5	5	-5	5	μA

Notes:

- All voltages referenced to ground.
- Overshoot:
 3.3V and 2.5V: V_{IH} (AC) ≤ V_{DD} + 1.5V (Pulse width less than t_{kc} / 2)
 1.8V: V_{IH} (AC) ≤ V_{DD} + 0.5V (Pulse width less than t_{kc} / 2)
- Undershoot:
 3.3V and 2.5V: V_{IL} (AC) ≥ -1.5V (Pulse width less than t_{kc} / 2)
 1.8V: V_{IL} (AC) ≥ -0.5V (Pulse width less than t_{kc} / 2)

POWER SUPPLY CHARACTERISTICS⁽¹⁾ (Over Operating Range)

Symbol	Parameter	Test Conditions	Temp. range	6.5 MAX		7.5 MAX		Unit
				x18	x36	x18	x36	
I _{CC}	AC Operating Supply Current	Device Selected,	Com.	120	120	110	110	mA
		OE = V _{IH} , ZZ ≤ V _{IL} ,	Ind.	130	130	120	120	
		All Inputs ≤ 0.2V or ≥ V _{DD} - 0.2V, Auto. Cycle Time ≥ t _{kc} min.	Auto.	-	-	125	125	
I _{SB}	Standby Current TTL Input	Device Deselected,	Com.	65	65	65	65	mA
		V _{DD} = Max.,	Ind.	70	70	70	70	
		All Inputs ≤ V _{IL} or ≥ V _{IH} , ZZ ≤ V _{IL} , f = Max.	Auto.	-	-	75	75	
I _{SBI}	Standby Current CMOS Input	Device Deselected,	Com.	50	50	50	50	mA
		V _{DD} = Max.,	Ind.	55	55	55	55	
		V _{IN} ≤ V _{SS} + 0.2V or ≥ V _{DD} - 0.2V f = 0	Auto.	-	-	60	60	

Note:

- MODE pin has an internal pullup and should be tied to V_{DD} or V_{SS}. It exhibits ±100 μA maximum leakage current when tied to ≤ V_{SS} + 0.2V or ≥ V_{DD} - 0.2V.

CAPACITANCE^(1,2)

Symbol	Parameter	Conditions	Max.	Unit
C _{IN}	Input Capacitance	V _{IN} = 0V	6	pF
C _{OUT}	Input/Output Capacitance	V _{OUT} = 0V	8	pF

Notes:

1. Tested initially and after any design or process changes that may affect these parameters.
2. Test conditions: T_A = 25°C, f = 1 MHz, V_{DD} = 3.3V.

3.3V I/O AC TEST CONDITIONS

Parameter	Unit
Input Pulse Level	0V to 3.0V
Input Rise and Fall Times	1.5 ns
Input and Output Timing and Reference Level	1.5V
Output Load	See Figures 1 and 2

AC TEST LOADS

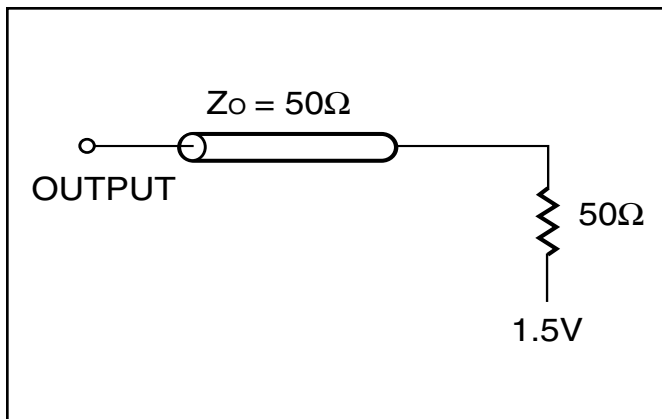


Figure 1

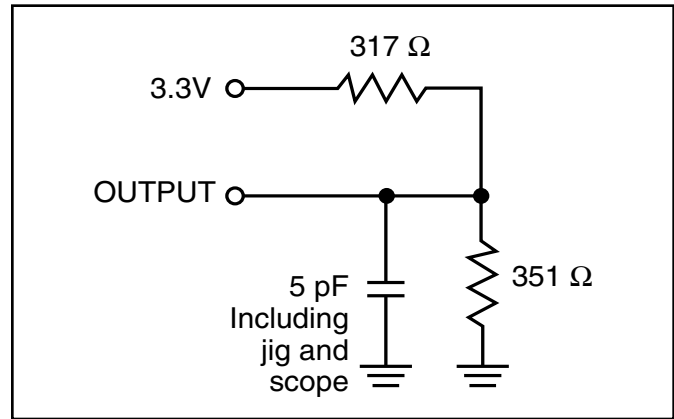


Figure 2

2.5V I/O AC TEST CONDITIONS

Parameter	Unit
Input Pulse Level	0V to 2.5V
Input Rise and Fall Times	1.5 ns
Input and Output Timing and Reference Level	1.25V
Output Load	See Figures 3 and 4

2.5V I/O OUTPUT LOAD EQUIVALENT

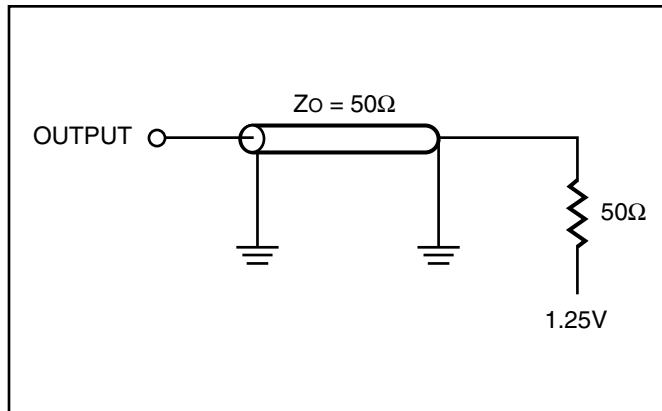


Figure 3

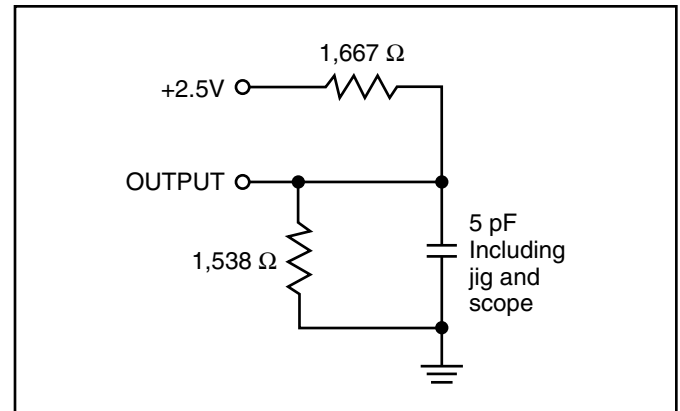


Figure 4

1.8V I/O AC TEST CONDITIONS

Parameter	Unit
Input Pulse Level	0V to 1.8V
Input Rise and Fall Times	1.5 ns
Input and Output Timing and Reference Level	0.9V
Output Load	See Figures 5 and 6

1.8V I/O OUTPUT LOAD EQUIVALENT

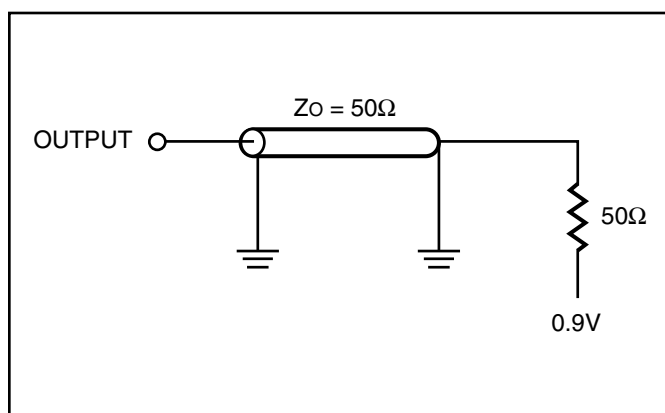


Figure 5

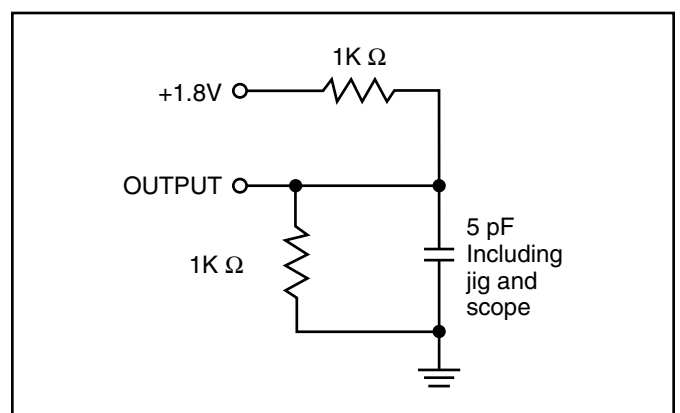


Figure 6

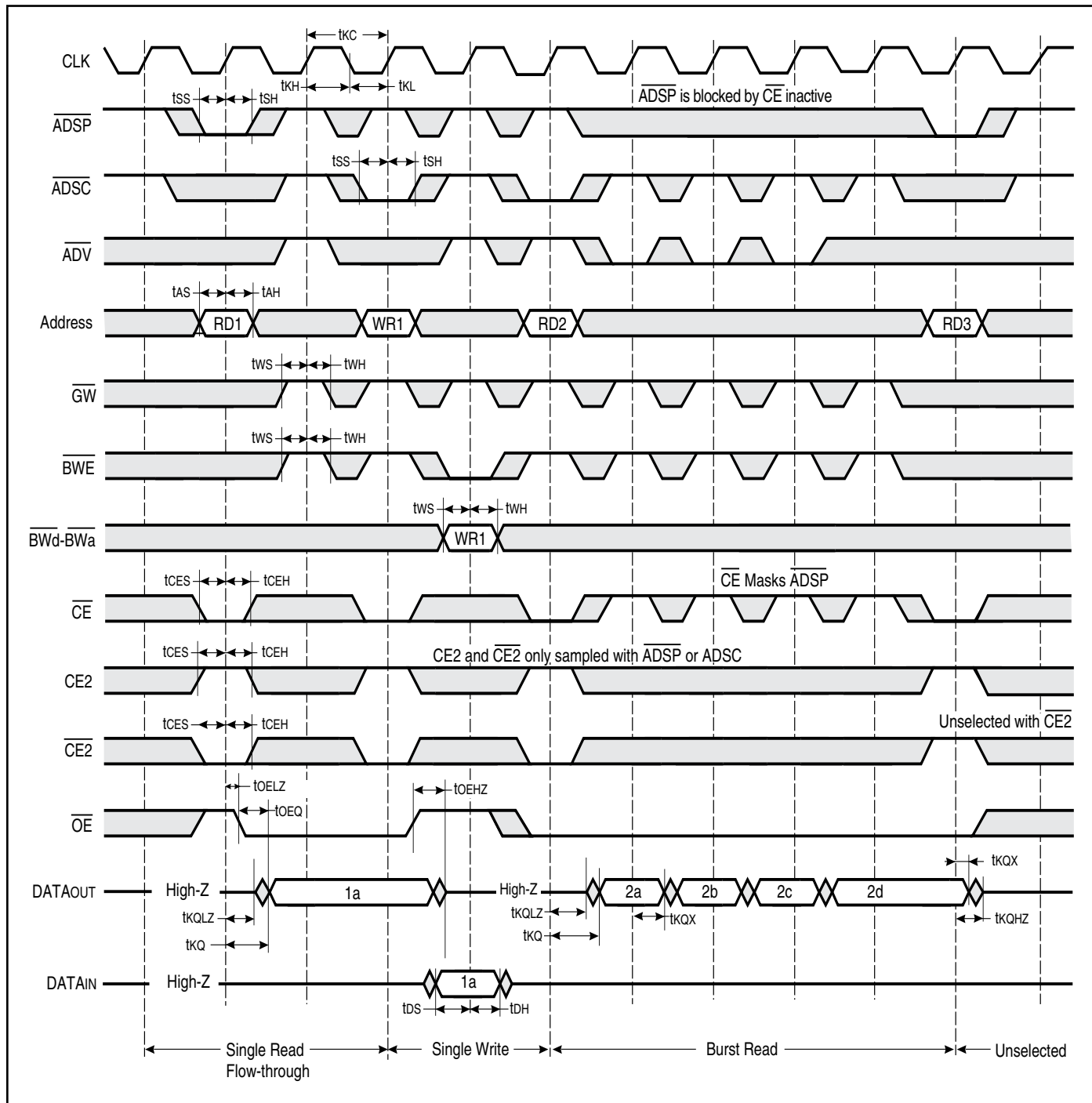
READ/WRITE CYCLE SWITCHING CHARACTERISTICS⁽¹⁾ (Over Operating Range)

Symbol	Parameter	6.5		7.5		Unit
		Min.	Max.	Min.	Max.	
fmax	Clock Frequency	—	133	—	117	MHz
tkc	Cycle Time	7.5	—	8.5	—	ns
tkh	Clock High Time	2.2	—	2.5	—	ns
tkl	Clock Low Time	2.2	—	2.5	—	ns
tkq	Clock Access Time	—	6.5	—	7.5	ns
tkqx ⁽²⁾	Clock High to Output Invalid	2.5	—	2.5	—	ns
tkqlz ^(2,3)	Clock High to Output Low-Z	2.5	—	2.5	—	ns
tkqhz ^(2,3)	Clock High to Output High-Z	—	3.8	—	4.0	ns
toeq	Output Enable to Output Valid	—	3.2	—	3.4	ns
toelz ^(2,3)	Output Enable to Output Low-Z	0	—	0	—	ns
toehz ^(2,3)	Output Disable to Output High-Z	—	3.5	—	3.5	ns
tas	Address Setup Time	1.5	—	1.5	—	ns
tss	Address Status Setup Time	1.5	—	1.5	—	ns
tws	Read/Write Setup Time	1.5	—	1.5	—	ns
tcES	Chip Enable Setup Time	1.5	—	1.5	—	ns
tAVS	Address Advance Setup Time	1.5	—	1.5	—	ns
tDS	Data Setup Time	1.5	—	1.5	—	ns
tAH	Address Hold Time	0.5	—	0.5	—	ns
tSH	Address Status Hold Time	0.5	—	0.5	—	ns
tWH	Write Hold Time	0.5	—	0.5	—	ns
tCEH	Chip Enable Hold Time	0.5	—	0.5	—	ns
tAVH	Address Advance Hold Time	0.5	—	0.5	—	ns
tDH	Data Hold Time	0.5	—	0.5	—	ns
tPOWER ⁽⁴⁾	VDD (typical) to First Access	1	—	1	—	ms

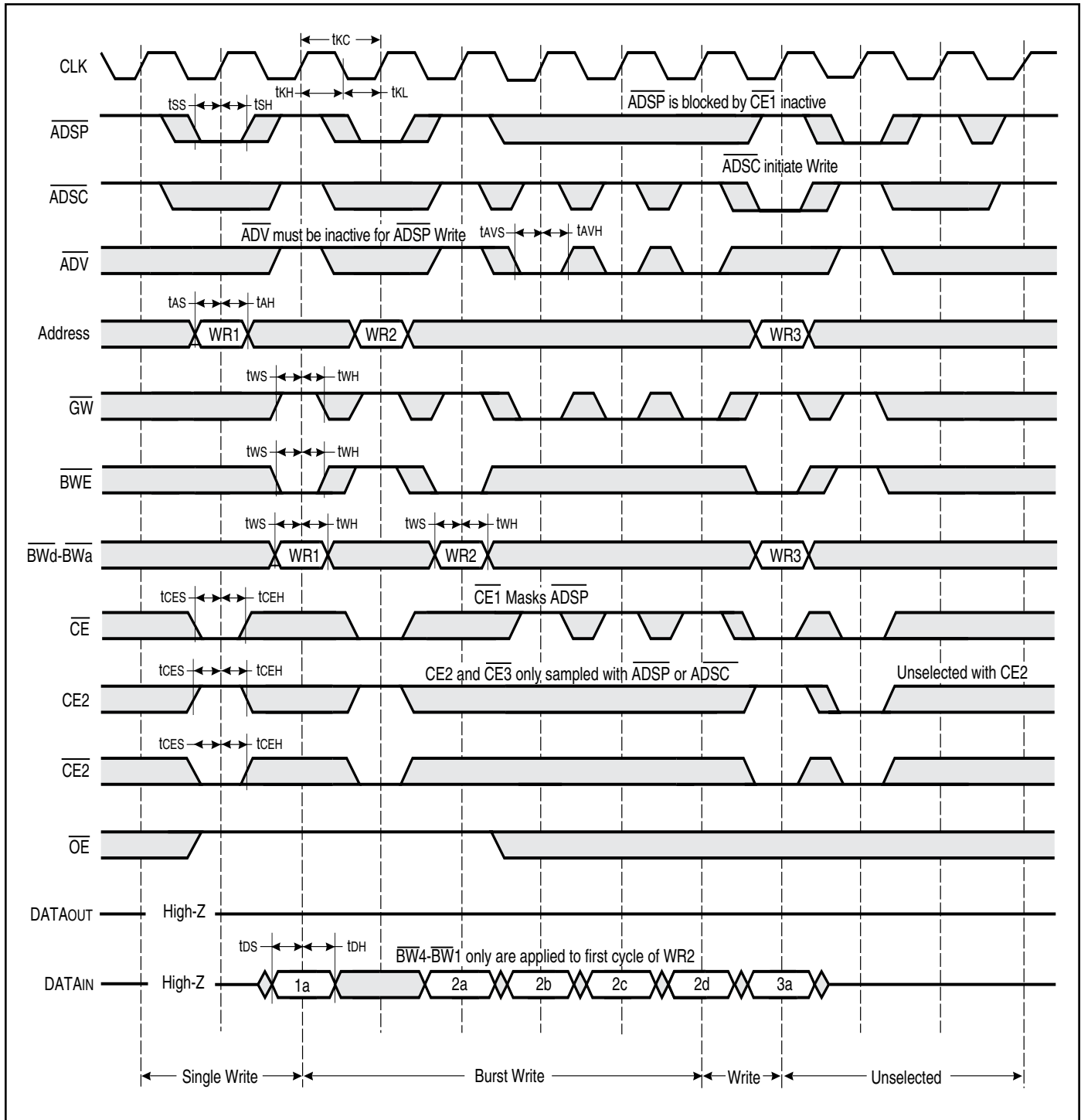
Notes:

1. Configuration signal MODE is static and must not change during normal operation.
2. Guaranteed but not 100% tested. This parameter is periodically sampled.
3. Tested with load in Figure 2.
4. tPOWER is the time that the power needs to be supplied above VDD (min) initially before READ or WRITE operation can be initiated.

READ/WRITE CYCLE TIMING



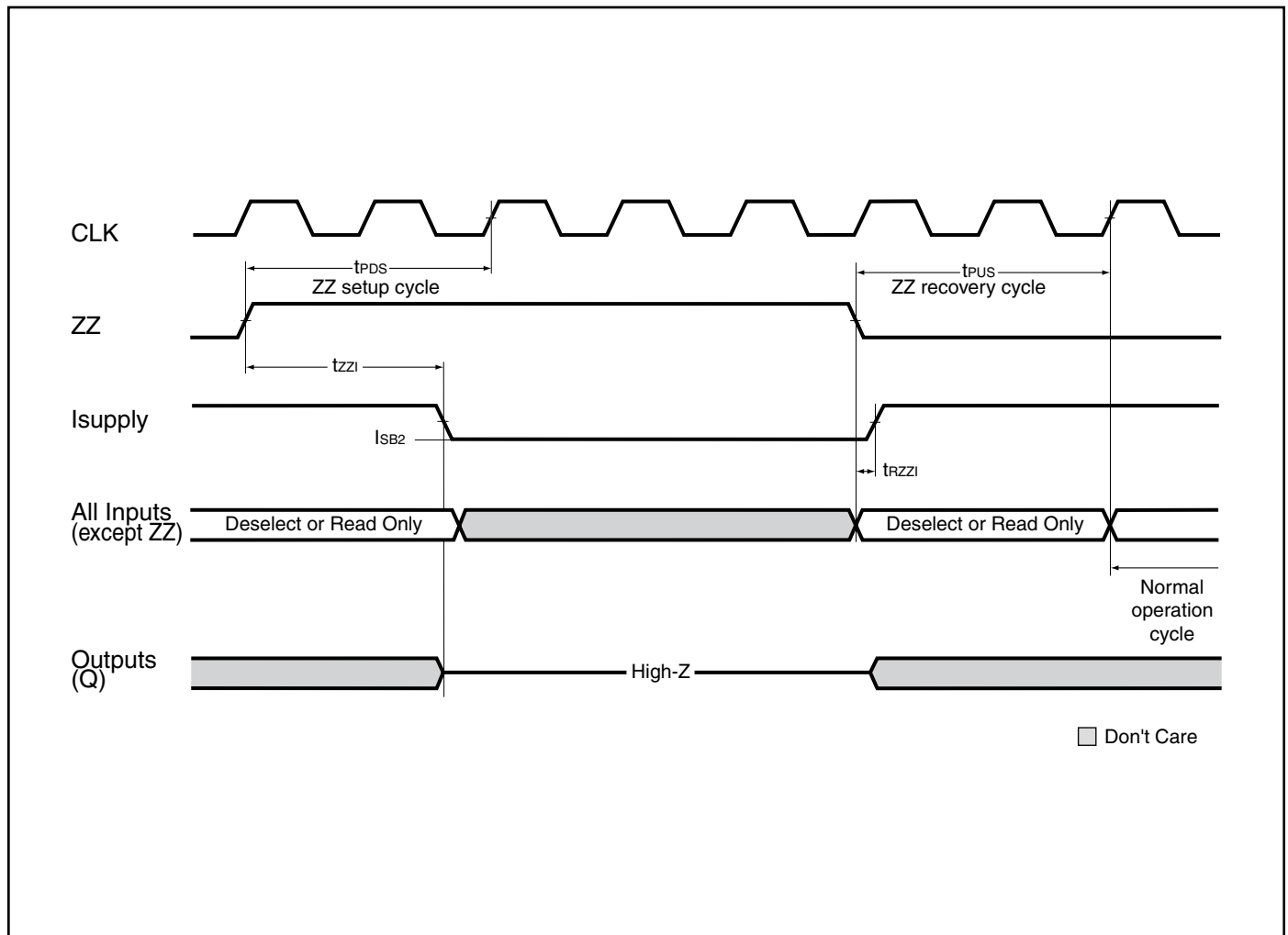
WRITE CYCLE TIMING



SNOOZE MODE ELECTRICAL CHARACTERISTICS

Symbol	Parameter	Conditions	Temp. Range	Min.	Max.	Unit
ISB2	Current during SNOOZE MODE	$ZZ \geq V_{ih}$	Com.	—	15	mA
			Ind.	—	20	
			Auto.	—	30	
tPDS	ZZ active to input ignored			—	2	cycle
tPUS	ZZ inactive to input sampled			2	—	cycle
tZZI	ZZ active to SNOOZE current			—	2	cycle
tRZZI	ZZ inactive to exit SNOOZE current			0	—	ns

SNOOZE MODE TIMING



IEEE 1149.1 SERIAL BOUNDARY SCAN (JTAG)

The serial boundary scan Test Access Port (TAP) is only available in the BGA package. This port operates in accordance with IEEE Standard 1149.1-1900, but does not include all functions required for full 1149.1 compliance. These functions from the IEEE specification are excluded because they place added delay in the critical speed path of the SRAM. The TAP controller operates in a manner that does not conflict with the performance of other devices using 1149.1 fully compliant TAPs.

DISABLING THE JTAG FEATURE

The SRAM can operate without using the JTAG feature. To disable the TAP controller, TCK must be tied LOW (Vss) to prevent clocking of the device. TDI and TMS are internally pulled up and may be disconnected. They may alternately be connected to VDD through a pull-up resistor. TDO should be left disconnected. On power-up, the device will start in a reset state which will not interfere with the device operation.

TEST ACCESS PORT (TAP) - TEST CLOCK

The test clock is only used with the TAP controller. All inputs are captured on the rising edge of TCK and outputs are driven from the falling edge of TCK.

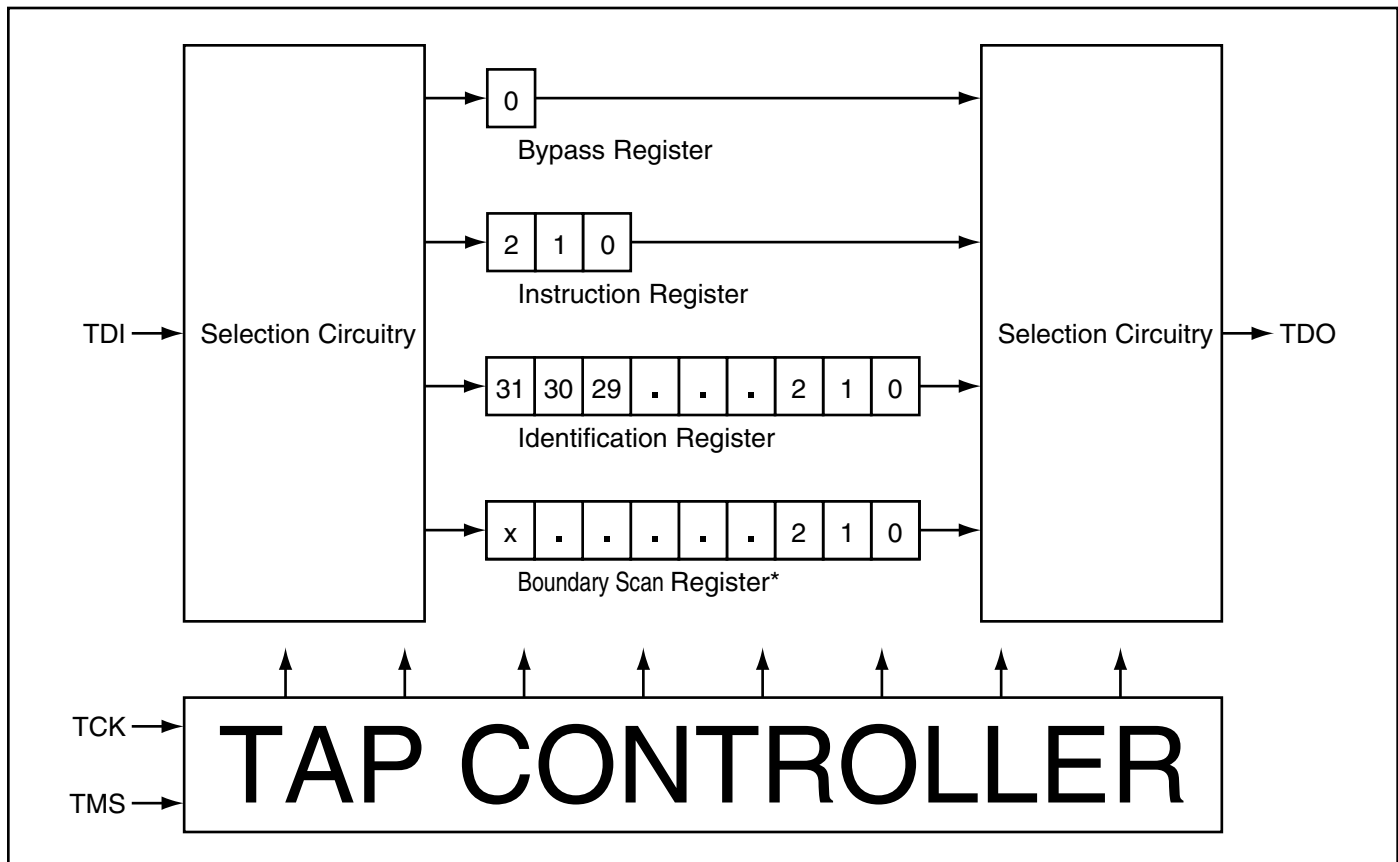
TEST MODE SELECT (TMS)

The TMS input is used to send commands to the TAP controller and is sampled on the rising edge of TCK. This pin may be left disconnected if the TAP is not used. The pin is internally pulled up, resulting in a logic HIGH level.

TEST DATA-IN (TDI)

The TDI pin is used to serially input information to the registers and can be connected to the input of any register. The register between TDI and TDO is chosen by the instruction loaded into the TAP instruction register. For information on instruction register loading, see the TAP Controller State Diagram. TDI is internally pulled up and can be disconnected if the TAP is unused in an application. TDI is connected to the Most Significant Bit (MSB) on any register.

TAP CONTROLLER BLOCK DIAGRAM



TEST DATA OUT (TDO)

The TDO output pin is used to serially clock data-out from the registers. The output is active depending on the current state of the TAP state machine (see TAP Controller State Diagram). The output changes on the falling edge of TCK and TDO is connected to the Least Significant Bit (LSB) of any register.

PERFORMING A TAP RESET

A Reset is performed by forcing TMS HIGH (V_{DD}) for five rising edges of TCK. RESET may be performed while the SRAM is operating and does not affect its operation. At power-up, the TAP is internally reset to ensure that TDO comes up in a high-Z state.

TAP REGISTERS

Registers are connected between the TDI and TDO pins and allow data to be scanned into and out of the SRAM test circuitry. Only one register can be selected at a time through the instruction registers. Data is serially loaded into the TDI pin on the rising edge of TCK and output on the TDO pin on the falling edge of TCK.

Instruction Register

Three-bit instructions can be serially loaded into the instruction register. This register is loaded when it is placed between the TDI and TDO pins. (See TAP Controller Block Diagram) At power-up, the instruction register is loaded with the IDCODE instruction. It is also loaded with the IDCODE instruction if the controller is placed in a reset state as previously described.

When the TAP controller is in the CaptureIR state, the two least significant bits are loaded with a binary “01” pattern to allow for fault isolation of the board level serial test path.

Bypass Register

To save time when serially shifting data through registers, it is sometimes advantageous to skip certain states. The bypass register is a single-bit register that can be placed between TDI and TDO pins. This allows data to be shifted through the SRAM with minimal delay. The bypass reg-

ister is set LOW (V_{SS}) when the BYPASS instruction is executed.

Boundary Scan Register

The boundary scan register is connected to all input and output pins on the SRAM. Several no connect (NC) pins are also included in the scan register to reserve pins for higher density devices. The x36 configuration has a 75-bit-long register and the x18 configuration also has a 75-bit-long register. The boundary scan register is loaded with the contents of the RAM Input and Output ring when the TAP controller is in the Capture-DR state and then placed between the TDI and TDO pins when the controller is moved to the Shift-DR state. The EXTEST, SAMPLE/PRELOAD and SAMPLE-Z instructions can be used to capture the contents of the Input and Output ring.

The Boundary Scan Order tables show the order in which the bits are connected. Each bit corresponds to one of the bumps on the SRAM package. The MSB of the register is connected to TDI, and the LSB is connected to TDO.

Scan Register Sizes

Register Name	Bit Size	Bit Size (x18) (x36)
Instruction	3	3
Bypass	1	1
ID	32	32
Boundary Scan	90	90

Identification (ID) Register

The ID register is loaded with a vendor-specific, 32-bit code during the Capture-DR state when the IDCODE command is loaded to the instruction register. The IDCODE is hardwired into the SRAM and can be shifted out when the TAP controller is in the Shift-DR state. The ID register has vendor code and other information described in the Identification Register Definitions table.

IDENTIFICATION REGISTER DEFINITIONS

Instruction Field	Description	256K x 36	512K x 18
Revision Number (31:28)	Reserved for version number.	xxxx	xxxx
Device Depth (27:23)	Defines depth of SRAM. 256K or 512K	00111	01000
Device Width (22:18)	Defines width of the SRAM. x36 or x18	00100	00011
ISSI Device ID (17:12)	Reserved for future use.	xxxxx	xxxxx
ISSI JEDEC ID (11:1)	Allows unique identification of SRAM vendor.	00001010101	00001010101
ID Register Presence (0)	Indicate the presence of an ID register.	1	1

TAP INSTRUCTION SET

Eight instructions are possible with the three-bit instruction register and all combinations are listed in the Instruction Code table. Three instructions are listed as RESERVED and should not be used and the other five instructions are described below. The TAP controller used in this SRAM is not fully compliant with the 1149.1 convention because some mandatory instructions are not fully implemented. The TAP controller cannot be used to load address, data or control signals and cannot preload the Input or Output buffers. The SRAM does not implement the 1149.1 commands EXTEST or INTEST or the PRELOAD portion of SAMPLE/PRELOAD; instead it performs a capture of the Inputs and Output ring when these instructions are executed. Instructions are loaded into the TAP controller during the Shift-IR state when the instruction register is placed between TDI and TDO. During this state, instructions are shifted from the instruction register through the TDI and TDO pins. To execute an instruction once it is shifted in, the TAP controller must be moved into the Update-IR state.

EXTEST

EXTEST is a mandatory 1149.1 instruction which is to be executed whenever the instruction register is loaded with all 0s. Because EXTEST is not implemented in the TAP controller, this device is not 1149.1 standard compliant. The TAP controller recognizes an all-0 instruction. When an EXTEST instruction is loaded into the instruction register, the SRAM responds as if a SAMPLE/PRELOAD instruction has been loaded. There is a difference between the instructions, unlike the SAMPLE/PRELOAD instruction, EXTEST places the SRAM outputs in a High-Z state.

IDCODE

The IDCODE instruction causes a vendor-specific, 32-bit code to be loaded into the instruction register. It also places the instruction register between the TDI and TDO pins and allows the IDCODE to be shifted out of the device when the TAP controller enters the Shift-DR state. The IDCODE instruction is loaded into the instruction register upon power-up or whenever the TAP controller is given a test logic reset state.

SAMPLE-Z

The SAMPLE-Z instruction causes the boundary scan register to be connected between the TDI and TDO pins when the TAP controller is in a Shift-DR state. It also places all SRAM outputs into a High-Z state.

SAMPLE/PRELOAD

SAMPLE/PRELOAD is a 1149.1 mandatory instruction. The PRELOAD portion of this instruction is not implemented, so the TAP controller is not fully 1149.1 compliant. When the SAMPLE/PRELOAD instruction is loaded to the instruction register and the TAP controller is in the Capture-DR state, a snapshot of data on the inputs and output pins is captured in the boundary scan register.

It is important to realize that the TAP controller clock operates at a frequency up to 10 MHz, while the SRAM clock runs more than an order of magnitude faster. Because of the clock frequency differences, it is possible that during the Capture-DR state, an input or output will under-go a transition. The TAP may attempt a signal capture while in transition (metastable state). The device will not be harmed, but there is no guarantee of the value that will be captured or repeatable results.

To guarantee that the boundary scan register will capture the correct signal value, the SRAM signal must be stabilized long enough to meet the TAP controller's capture set-up plus hold times (tcs and tch). To insure that the SRAM clock input is captured correctly, designs need a way to stop (or slow) the clock during a SAMPLE/PRELOAD instruction. If this is not an issue, it is possible to capture all other signals and simply ignore the value of the CLK and $\overline{\text{CLK}}$ captured in the boundary scan register.

Once the data is captured, it is possible to shift out the data by putting the TAP into the Shift-DR state. This places the boundary scan register between the TDI and TDO pins.

Note that since the PRELOAD part of the command is not implemented, putting the TAP into the Update to the Update-DR state while performing a SAMPLE/PRELOAD instruction will have the same effect as the Pause-DR command.

BYPASS

When the BYPASS instruction is loaded in the instruction register and the TAP is placed in a Shift-DR state, the bypass register is placed between the TDI and TDO pins. The advantage of the BYPASS instruction is that it shortens the boundary scan path when multiple devices are connected together on a board.

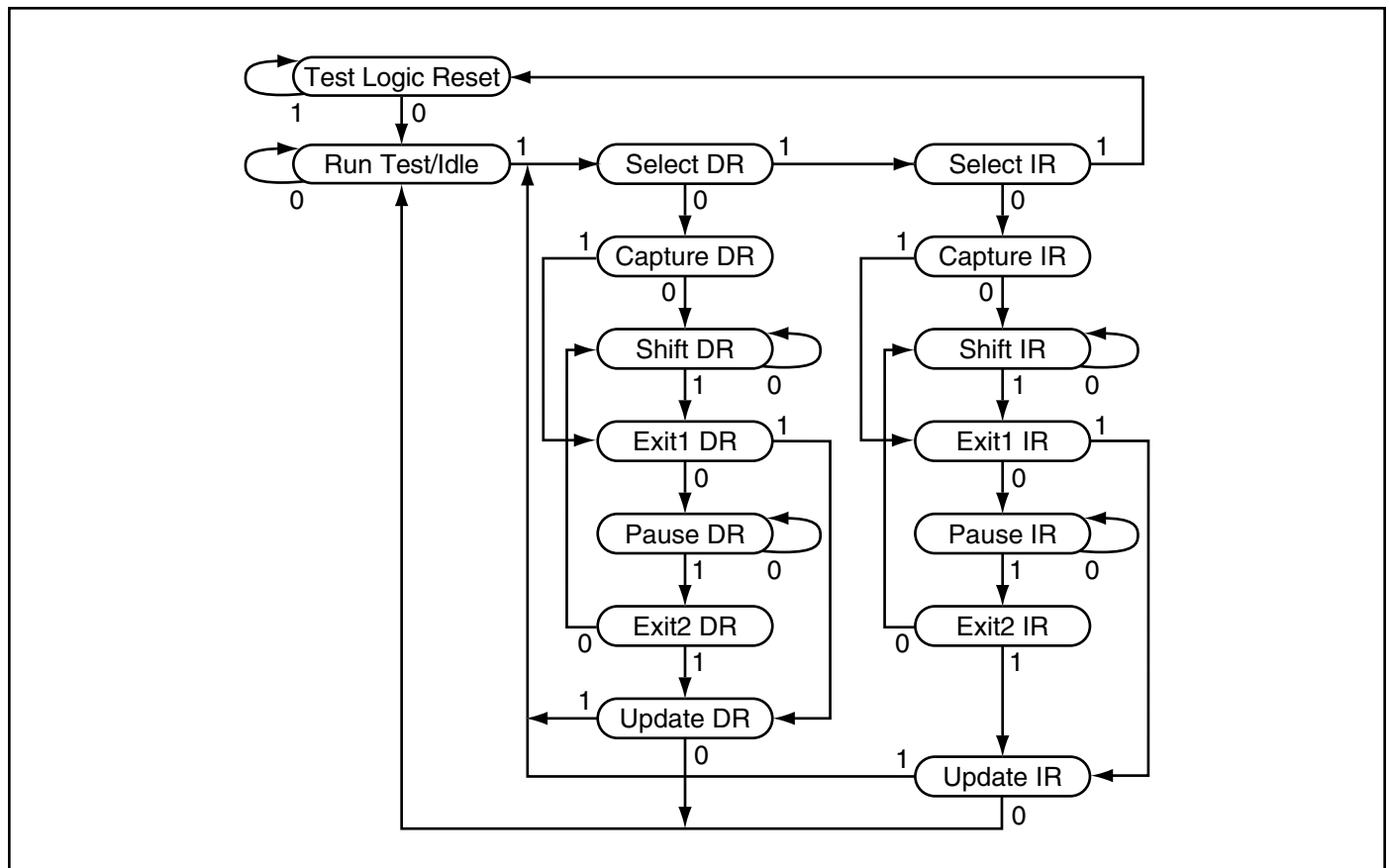
RESERVED

These instructions are not implemented but are reserved for future use. Do not use these instructions.

INSTRUCTION CODES

Code	Instruction	Description
000	EXTEST	Captures the Input/Output ring contents. Places the boundary scan register between the TDI and TDO. Forces all SRAM outputs to High-Z state. This instruction is not 1149.1 compliant.
001	IDCODE	Loads the ID register with the vendor ID code and places the register between TDI and TDO. This operation does not affect SRAM operation.
010	SAMPLE-Z	Captures the Input/Output contents. Places the boundary scan register between TDI and TDO. Forces all SRAM output drivers to a High-Z state.
011	RESERVED	Do Not Use: This instruction is reserved for future use.
100	SAMPLE/PRELOAD	Captures the Input/Output ring contents. Places the boundary scan register between TDI and TDO. Does not affect the SRAM operation. This instruction does not implement 1149.1 preload function and is therefore not 1149.1 compliant.
101	RESERVED	Do Not Use: This instruction is reserved for future use.
110	RESERVED	Do Not Use: This instruction is reserved for future use.
111	BYPASS	Places the bypass register between TDI and TDO. This operation does not affect SRAM operation.

TAP CONTROLLER STATE DIAGRAM



TAP Electrical Characteristics (2.5V and 3.3V Operating Range)

Symbol	Parameter	Test Conditions	Min.	Max.	Units
VOH1	Output HIGH Voltage	IOH = -2.0 mA	1.7	—	V
VOH2	Output HIGH Voltage	IOH = -100 μA	2.1	—	V
VOL1	Output LOW Voltage	IOL = 2.0 mA	—	0.7	V
VOL2	Output LOW Voltage	IOL = 100 μA	—	0.2	V
VIH	Input HIGH Voltage		1.7	VDD +0.3	V
VIL	Input LOW Voltage	IOLT = 2mA	-0.3	0.7	V
IX	Input Load Current	VSS ≤ V I ≤ VDDQ	-5	5	mA

TAP Electrical Characteristics (1.8V Operating Range)

Symbol	Parameter	Test Conditions	Min.	Max.	Units
VOH1	Output HIGH Voltage	IOH = -2.0 mA	VDD -0.4	—	V
VOL1	Output LOW Voltage	IOL = 2.0 mA	-0.3	0.5	V
VIH	Input HIGH Voltage		1.3	VDD +0.3	V
VIL	Input LOW Voltage	IOLT = 2mA	-0.3	0.7	V
IX	Input Load Current	VSS ≤ V I ≤ VDDQ	-5	5	mA

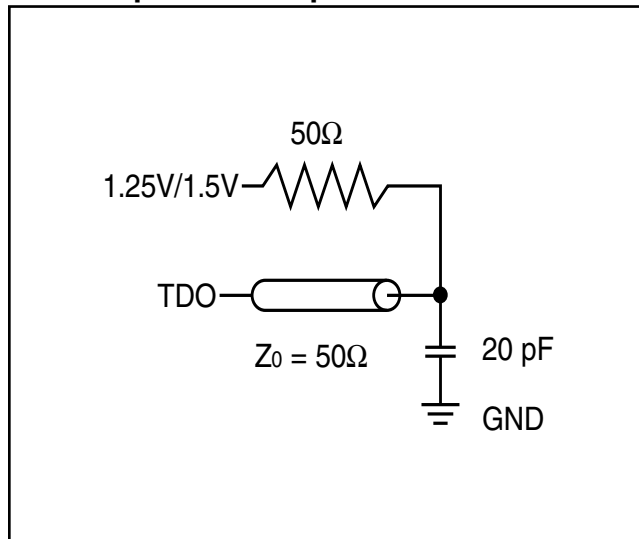
TAPAC ELECTRICAL CHARACTERISTICS(OVER OPERATING RANGE)

Parameter	Symbol	Min	Max	Units
TCK cycle time	tHHTH	100	—	ns
TCK high pulse width	tHTL	40	—	ns
TCK low pulse width	tTLTH	40	—	ns
TMS Setup	tMVTH	10	—	ns
TMS Hold	tHMX	10	—	ns
TDI Setup	tDVTH	10	—	ns
TDI Hold	tHDX	10	—	ns
TCK Low to Valid Data	tTLOV	—	20	ns

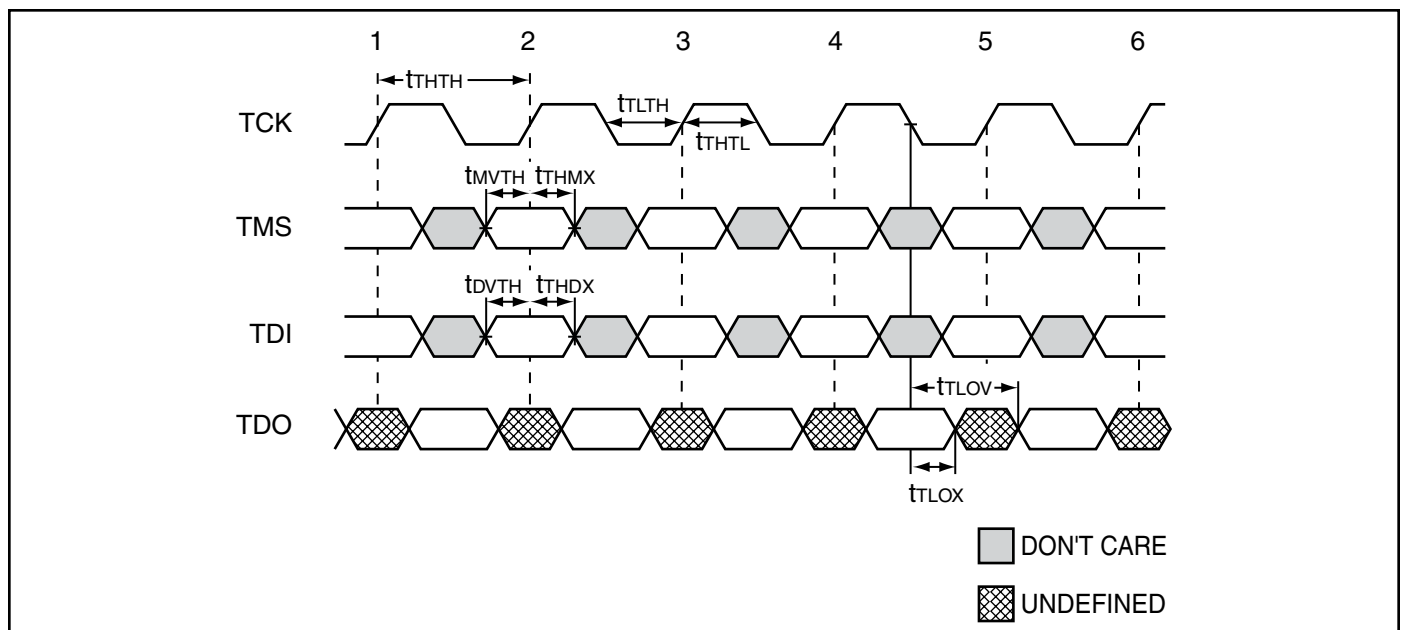
TAP AC TEST CONDITIONS (1.8V/2.5V/3.3V)

Input pulse levels	0 to 1.8V/0 to 2.5V/0 to 3.0V
Input rise and fall times	1.5ns
Input timing reference levels	0.9V/1.25V/1.5V
Output reference levels	0.9V/1.25V/1.5V
Test load termination supply voltage	0.9V/1.25V/1.5V

TAP Output Load Equivalent



TAP TIMING





119 BGA BOUNDARY SCAN ORDER

TBD

165 BGA BOUNDARY SCAN ORDER

165 BGA				
	x36		x18	
Bit #	Bump ID	Signal	Bump ID	Signal
1	N6	NC	N6	NC
2	N7	NC	N7	NC
3	N10	NC	N10	NC
4	P11	A8	P11	A8
5	P8	A18	P8	A18
6	R8	A17	R8	A17
7	R9	A16	R9	A16
8	P9	A15	P9	A15
9	P10	A14	P10	A14
10	R10	A13	R10	A13
11	R11	A12	R11	A12
12	H11	ZZ	H11	ZZ
13	N11	DQa0	N11	NC
14	M11	DQa1	M11	NC
15	L11	DQa2	L11	NC
16	M10	DQa3	M10	DQa8
17	L10	DQa4	L10	DQa7
18	K11	DQa5	K11	NC
19	J11	DQa6	J11	NC
20	K10	DQa7	K10	DQa6
21	J10	DQa8	J10	DQa5
22	H9	NC	H9	NC
23	H10	NC	H10	NC
24	G11	DQb8	G11	DQa4
25	F11	DQb7	F11	DQa3
26	G10	DQb6	G10	NC
27	E11	DQb5	E11	DQa2
28	D11	DQb4	D11	DQa1
29	F10	DQb3	C11	DQa0
30	E10	DQb2	E10	NC
31	D10	DQb1	D10	NC
32	C11	DQb0	F10	NC
33	A11	NC	A11	A19
34	B11	NC	B11	NC
35	A10	A11	A10	A11
36	B10	A10	B10	A10
37	A9	/ADV	A9	/ADV
38	B9	/ADSP	B9	/ADSP
39	C10	NC	C10	NC
40	A8	/ADSC	A8	/ADSC

165 BGA				
	x36		x18	
Bit #	Bump ID	Signal	Bump ID	Signal
41	B8	/OE	B8	/OE
42	A7	/BWE	A7	/BWE
43	B7	/GW	B7	/GW
44	B6	CLK	B6	CLK
45	A6	/CE2	A6	/CE2
46	B5	/Bwa	B5	/Bwa
47	A5	/Bwb	A5	NC
48	A4	/Bwc	A4	/Bwb
49	B4	/Bwd	B4	NC
50	B3	CE2	B3	CE2
51	A3	/CE1	A3	/CE1
52	A2	A7	A2	A7
53	B2	A6	B2	A6
54	C2	NC	C2	NC
55	B1	NC	B1	NC
56	A1	NC	A1	NC
57	C1	DQc0	C1	NC
58	D1	DQc1	D1	NC
59	E1	DQc2	E1	NC
60	D2	DQc3	D2	DQb8
61	E2	DQc4	E2	DQb7
62	F1	DQc5	F1	NC
63	G1	DQc6	G1	NC
64	F2	DQc7	F2	DQb6
65	G2	DQc8	G2	DQb5
66	H1	NC	H1	NC
67	H2	NC	H2	NC
68	H3	NC	H3	NC
69	J1	DQd8	J1	DQb4
70	K1	DQd7	K1	DQb3
71	J2	DQd6	J2	NC
72	L1	DQd5	L1	DQb2
73	M1	DQd4	M1	DQb1
74	K2	DQd3	N1	DQb0
75	L2	DQd2	L2	NC
76	M2	DQd1	M2	NC
77	N1	DQd0	K2	NC
78	N2	NC	N2	NC
79	P1	NC	P1	NC
80	R1	MODE	R1	MODE

Continued on next page



165 BGA BOUNDARY SCAN ORDER

165 BGA				
	x36		x18	
Bit #	Bump ID	Signal	Bump ID	Signal
81	R2	NC	R2	NC
82	P3	A5	P3	A5
83	R3	A4	R3	A4
84	P2	NC	P2	NC
85	P4	A2	P4	A2
86	R4	A3	R4	A3
87	N5	NC	N5	NC
88	P6	A1	P6	A1
89	R6	A0	R6	A0
90	*	Int	*	Int



IS61(64)LF25636B, IS61VF/VVF25636B
 IS61(64)LF51218B, IS61VF/VVF51218B

ORDERING INFORMATION (V_{DD} = 3.3V/V_{DDQ} = 2.5V/3.3V)

Industrial Range: -40°C to +85°C

Configuration	Access Time	Order Part Number	Package ⁽¹⁾
256Kx36	6.5	IS61LF25636B-6.5TQI	100 QFP, 3CE
		IS61LF25636B-6.5B2I	119 BGA
		IS61LF25636B-6.5B3I	165 BGA
256Kx36	7.5	IS61LF25636B-7.5TQI	100 QFP, 3CE
		IS61LF25636B-7.5TQLI	100 QFP, 3CE, Lead-free
		IS61LF25636B-7.5B2I	119 BGA
		IS61LF25636B-7.5B3I	165 BGA
512Kx18	6.5	IS61LF51218B-6.5TQI	100 QFP, 3CE
		IS61LF51218B-6.5B2I	119 BGA
		IS61LF51218B-6.5B3I	165 BGA
512Kx18	7.5	IS61LF51218B-7.5TQI	100 QFP, 3CE
		IS61LF51218B-7.5TQLI	100 QFP, 3CE, Lead-free
		IS61LF51218B-7.5B2I	119 BGA
		IS61LF51218B-7.5B3I	165 BGA

Note:

1. For 100 QFP, 2CE option contact SRAM Marketing at sram@issi.com

Automotive (A3) Range: -40°C to +125°C

Configuration	Access Time	Order Part Number	Package ⁽¹⁾
256Kx36	7.5	IS64LF25636B-7.5TQA3	100 QFP, 3CE
		IS64LF25636B-7.5TQLA3	100 QFP, 3CE, Lead-free
		IS64LF25636B-7.5B2A3	119 BGA
		IS64LF25636B-7.5B3A3	165 BGA
		IS64LF25636B-7.5B3LA3	165 BGA, Lead-free
512Kx18	7.5	IS64LF51218B-7.5TQA3	100 QFP, 3CE
		IS64LF51218B-7.5TQLA3	100 QFP, 3CE, Lead-free
		IS64LF51218B-7.5B2A3	119 BGA
		IS64LF51218B-7.5B3A3	165 BGA

Note:

1. For 100 QFP, 2CE option contact SRAM Marketing at sram@issi.com



ORDERING INFORMATION (V_{DD} = 2.5V /V_{DDQ} = 2.5V)

Industrial Range: -40°C to +85°C

Configuration	Access Time	Order Part Number	Package ⁽¹⁾
256Kx36	6.5	IS61VF25636B-6.5TQI	100 QFP, 3CE
		IS61VF25636B-6.5B2I	119 BGA
		IS61VF25636B-6.5B3I	165 BGA
256Kx36	7.5	IS61VF25636B-7.5TQI	100 QFP, 3CE
		IS61VF25636B-7.5B2I	119 BGA
		IS61VF25636B-7.5B3I	165 BGA
512Kx18	6.5	IS61VF51218B-6.5TQI	100 QFP, 3CE
		IS61VF51218B-6.5B2I	119 BGA
		IS61VF51218B-6.5B3I	165 BGA
512Kx18	7.5	IS61VF51218B-7.5TQI	100 QFP, 3CE
		IS61VF51218B-7.5B2I	119 BGA
		IS61VF51218B-7.5B3I	165 BGA

Note:

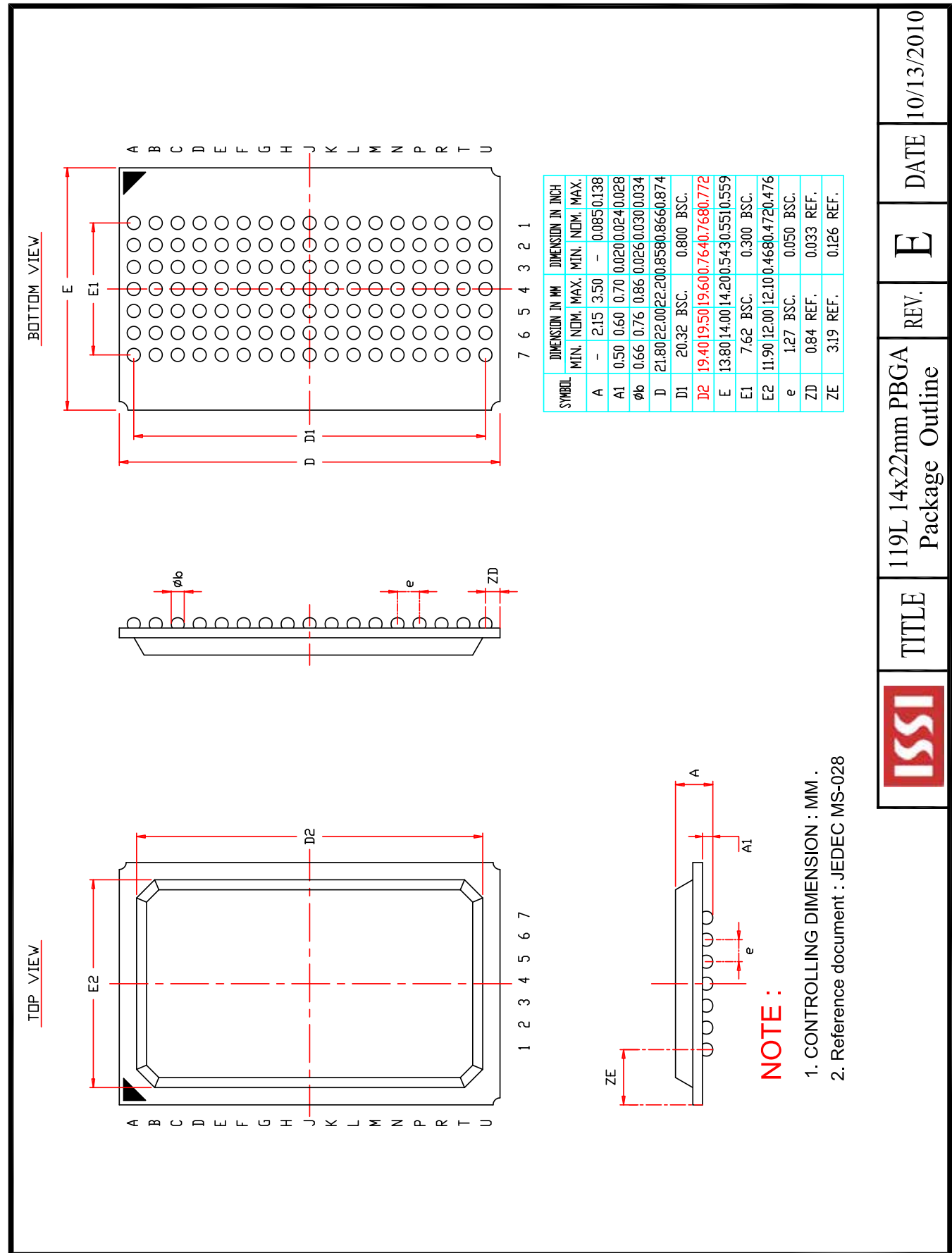
1. For 100 QFP, 2CE option contact SRAM Marketing at sram@issi.com

Automotive (A3) Range: -40°C to +125°C

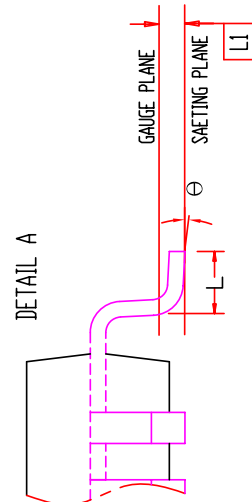
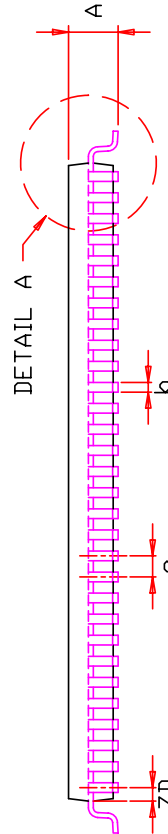
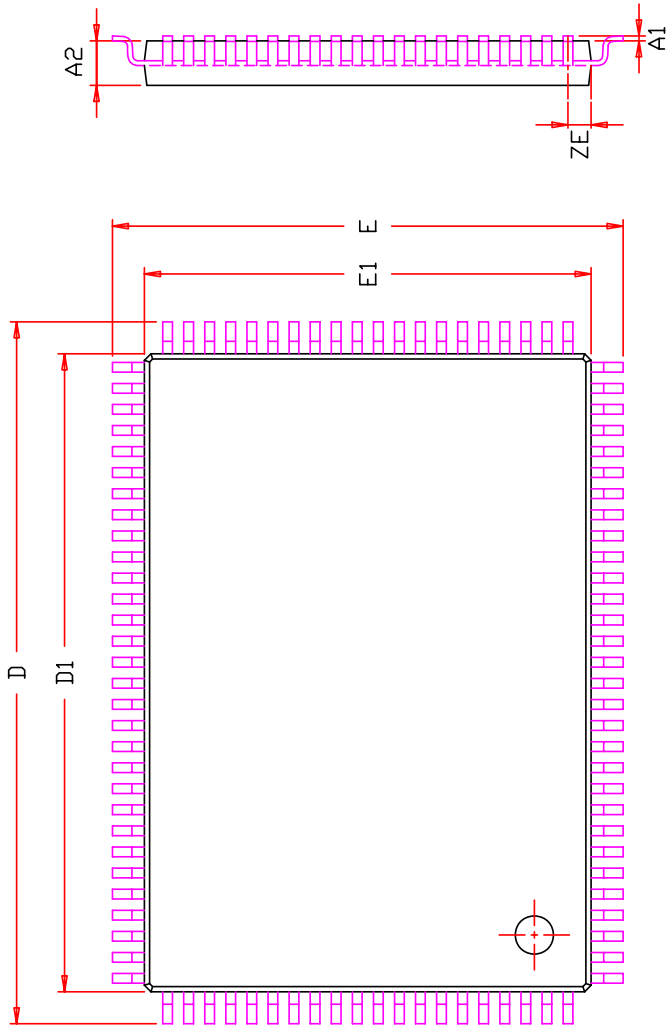
Configuration	Access Time	Order Part Number	Package ⁽¹⁾
256Kx36	7.5	IS64VF25636B-7.5TQA3	100 QFP, 3CE
		IS64VF25636B-7.5TQLA3	100 QFP, 3CE, Lead-free
		IS64VF25636B-7.5B2A3	119 BGA
		IS64VF25636B-7.5B3A3	165 BGA
512Kx18	7.5	IS64VF51218B-7.5TQA3	100 QFP, 3CE
		IS64VF51218B-7.5TQLA3	100 QFP, 3CE, Lead-free
		IS64VF51218B-7.5B2A3	119 BGA
		IS64VF51218B-7.5B3A3	165 BGA

Note:

1. For 100 QFP, 2CE option contact SRAM Marketing at sram@issi.com



	TITLE	119L 14x22mm PBGA Package Outline	REV.	E	DATE	10/13/2010
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SYMBOL	DIMENSION IN MM			DIMENSION IN INCH		
	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.
A	1.40		1.60	0.055		0.063
A1	0.05		0.15	0.002		0.006
A2	1.35	1.40	1.45	0.053	0.055	0.057
b	0.22	0.30	0.38	0.009	0.012	0.015
D	21.90	22.00	22.10	0.862	0.866	0.870
D1	19.90	20.00	20.10	0.783	0.787	0.791
E	15.90	16.00	16.10	0.626	0.630	0.634
E1	13.90	14.00	14.10	0.547	0.551	0.555
e	0.65 BSC.			0.026 BSC.		
L	0.45	0.60	0.75	0.018	0.024	0.030
L1	0.25 BSC.			0.010 BSC.		
ZD	0.575 REF.			0.023 REF.		
ZE	0.825 REF.			0.032 REF.		
θ	0	3.5°	7°	0	3.5°	7°

NOTE :

1. CONTROLLING DIMENSION : MM
2. DIMENSION D1 AND E1 DO NOT INCLUDE MOLD PROTRUSION.
3. DIMENSION b DOES NOT INCLUDE DAMBAR PROTRUSION/INTRUSION.



TITLE

100L14x20x1.4mm LQFP
 (Footprint : 2.0 mm)
 Package Outline

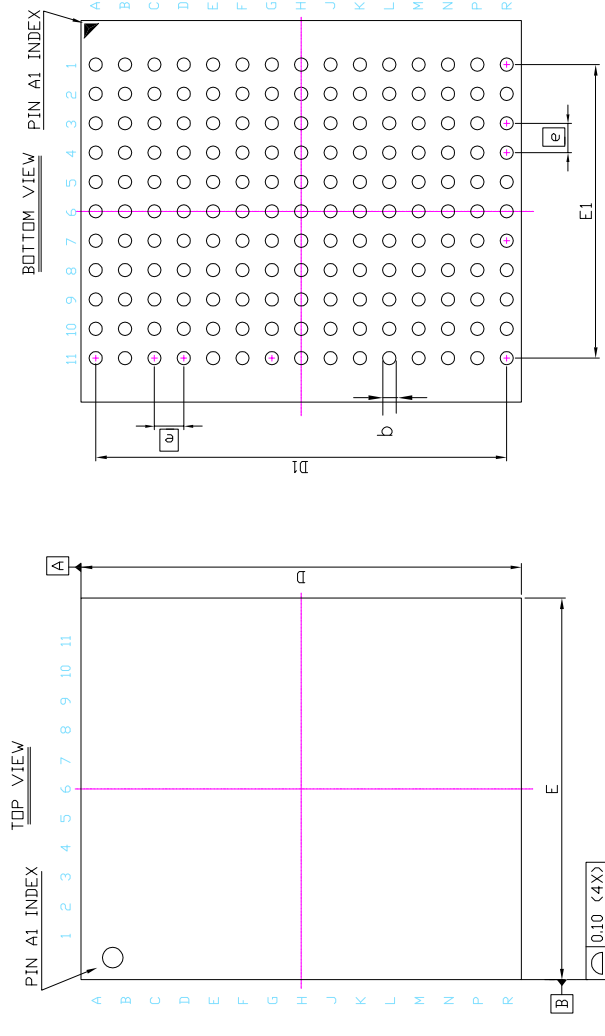
REV.

F

DATE

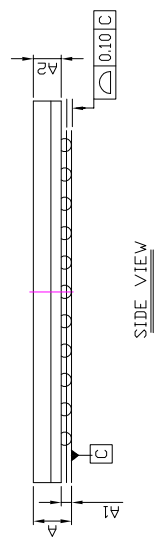
09/01/2009

280-600-011 REV. A



SYM.	DIMENSION (mm)			DIMENSION (inch)		
	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.
A	—	—	1.20	—	—	0.047
A1	0.25	0.35	0.40	0.010	0.014	0.016
A2	—	0.79	—	—	0.031	—
b	0.40	0.45	0.50	0.016	0.018	0.020
D	14.90	15.00	15.10	0.587	0.591	0.594
D1	13.90	14.00	14.10	0.547	0.551	0.555
E	12.90	13.00	13.10	0.508	0.512	0.516
E1	9.90	10.00	10.10	0.390	0.394	0.398
E	1.00 BSC			0.039 BSC		

NOTE :
 1. CONTROLLING DIMENSION : MM .



	TITLE	165L 13x15mm TF-BGA Package Outline	REV. B	DATE 08/28/2008
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Looking for pricing, stock, or lifecycle information?

Click below to explore more details on WIN SOURCE:

- ⊖ [View IS64LF25636B-7.5B3LA3 on WIN SOURCE](#)
- ⊖ [ISSI, Integrated Silicon Solution Inc Information](#)

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- ✓ Obsolete Management
- ✓ Cost Control Management
- ✓ Shortage Management
- ✓ Alternative Solution
- ✓ Excess Inventory Management